ABSTRACT OF THE DISCLOSURE

A light-emitting diode has a case having a concave portion, a reflection mirror obtained by forming metal on the concave portion, and a lead to one end of which a light-emitting element is attached. A cavity including the concave portion of the case is filled with an accelerated curing epoxy resin. The epoxy resin is cured so that the epoxy resin, the reflection mirror and the case are formed into a sandwich structure. With such a structure, a light-emitting diode free of wrinkles and cracks on the reflection mirror is provided. Further, at the time of handling or transportation, the reflection mirror is not damaged. Moreover, during reflow soldering, at the time of solder-mounting the light-emitting diode to a printed circuit board, thermal deformation, such as wrinkling and cracking of the reflection mirror is completely prevented.